

Title (en)  
Connecting system

Title (de)  
Verbindungssystem

Title (fr)  
Système de raccordement

Publication  
**EP 1600626 A1 20051130 (EN)**

Application  
**EP 04012810 A 20040528**

Priority  
EP 04012810 A 20040528

Abstract (en)  
A connecting device (1) and a connector (14) form a connecting arrangement. The connecting device (1) comprises a connecting element (2) having a tubular recess (3) and having a first connecting part (4). The connecting device (1) further comprises a thread part (5) being designed for forming a threading connection with a mating thread (16) formed in the connector (14) the connecting device (1) further comprises an intermediate connecting element (8) having a tubular recess (9) and having on one of its free ends a second connecting part (10) and having on the other one of its free ends a third connecting part (12). The first and second connecting parts (4, 10) are designed for forming a joint with either the first or the second connecting part (4, 10) having a tapered recess and the other one of the first or second connecting part (4, 10) being spherically shaped. The third connecting part (12) is designed for forming a joint with a fourth connecting part (18) of the connector (14) with either the third or the fourth connecting part (12, 18) having a tapered recess and the other one of the third or fourth connecting part (12, 18) being spherically shaped.  
<IMAGE>

IPC 1-7  
**F02M 55/00**

IPC 8 full level  
**F02M 55/00** (2006.01); **F02M 55/02** (2006.01)

CPC (source: EP)  
**F02M 55/005** (2013.01); **F02M 55/025** (2013.01)

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